

F11 Series

☑ CHF11-R315M75K-NB





X Application & Features

- RF.Wireless
- Automotive Equipment at Other
- 11.0×4.5×3.2mm Metal Package
- This specification shall cover the characteristics of 1-port SAW resonator with 315.000M used for remote-control security.

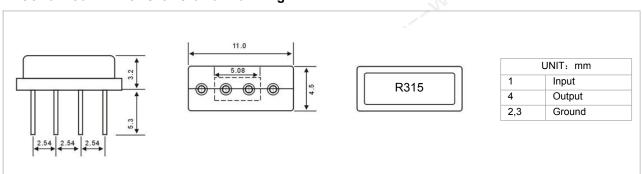
X Maximum Rating

Rating	Value	Unit	
CW RF power dissipation	P	10	dBm
DC voltage between any terminals	V _{DC}	±30	V
Operating temperature range	T _A	-40 ~ +85	°C
Storage temperature range	T _{stg}	-40 ~ +85	°C

X Electronic Characteristics

Characteristic		Sym	Minimum	Typical	Maximum	Unit
Center Frequency (+25℃)	Absolute Frequency	f _C	314.925	315.000	315.075	MHz
	Tolerance from 315.000 MHz	Δf_{C}		±75		kHz
Insertion Loss		1L		1.4	2.0	dB
Quality Factor	Unloaded Q	Q_U	8.000	11.90		
	50 Ω Loaded Q	Q_L	1000	1900		
Temperature Stability	Turnover Temperature	T ₀	10	25	40	$^{\circ}$
	Turnover Frequency	f ₀		fo±2.7		kHz
	Frequency Temperature Coefficient	FTC		0.032		ppm/°C²
Frequency Aging	Absolute Value during the First Year	f _A		≤10		ppm/yr
DC Insulation Resistance Between Any Two Terminals			1.0			MΩ
RF Equivalent RLC Model	Motional Resistance	R _M		19	23	Ω
	Motional Inductance	L _M		114.2958	100	μН
	Motional Capacitance	См		2.2358		pF
	Shunt Static Capacitance	C ₀	2.3	2.6	2.9	pF

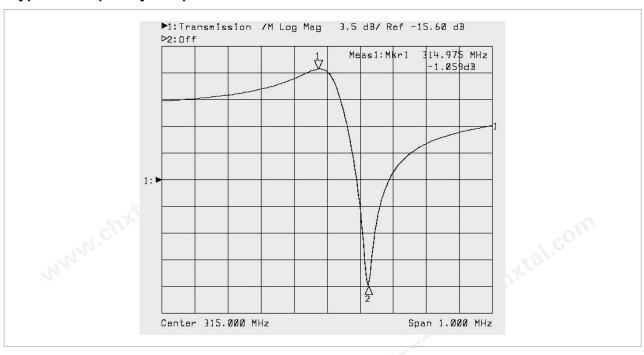
X Mechanical Dimensions and Marking



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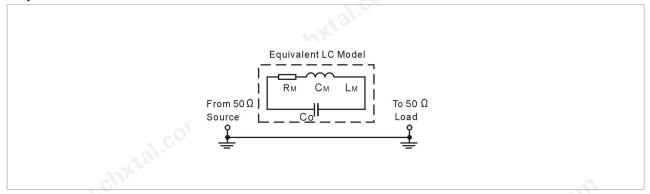


X Typical Frequency Response



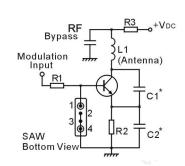
X Equivalent LC Model

X Test Circuit

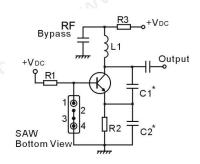


X Typical Application Circuits

1) Low-Power Transmitter Application



2) Local Oscillator Application



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声表谐振器 SAW Resonator - F11



ShenZhen ChenHang Technologies Co,.Ltd



X Environment Characteristic

1 Thermal Shock:

The components shall remain within the electrical specifications after being kept at the condition of heat cycle conditions: TA=-40 $^{\circ}$ ±3 $^{\circ}$, TB=85 $^{\circ}$ ±2 $^{\circ}$, t1=t2=30min, switch time≤3min& cycle time: 100 times, recovery time: 2h±0.5h.

2 Resistance to solder heat

Submerge the device terminals into the solder bath at $260\,^{\circ}$ C $\pm 5\,^{\circ}$ C for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 2.2.

3 Solder ability

Submerge the device terminals into the solder bath at 245 $^{\circ}$ C ±5 $^{\circ}$ C for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 2.2

4 The Temperature Storage:

- 4.1 High Temperature Storage: The components shall remain within the electrical specifications after being kept at the $85\%\pm2\%$ for 500h, recovery time: $2h\pm0.5h$.
- 4.2 Low Temperature Storage: The components shall remain within the electrical specifications after being kept at the $-40\,^{\circ}\text{C}\pm3\,^{\circ}\text{C}$ for 500h, recovery time : $2\text{h}\pm0.5\text{h}$.

5 Humidity test:

The components shall remain within the electrical specifications after being kept at the condition of ambient temperature $60\,^{\circ}\text{C}\pm2\,^{\circ}\text{C}$, and 90~96% RH for 500h.

6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m for 3 times. The resonator shall fulfill the specifications in 2.2.

7 Vibration

Subject the device to the vibration for 2 hour each in X, Y and Z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The resonator shall fulfill the specifications in 2.2.

X Remark

1 Static voltage

Static voltage between signal load & ground may cause deterioration &destruction of the component. Please avoid static voltage.

2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.